

You are in: Components | Memory

COMPONENTS

- Analogue & Discretetes
Displays and Opto
Memory
Micros & DSP
Passives
FPGAs & Asics

SIGN UP TO

Table with 2 columns: Category (Email Newsletters, RSS Feeds, Digital Magazine, Print Magazine, Technical Papers, Events, Media Centre) and Description.

WORK BREAK

- Photo Stories
Blogs
Video
Sudoku
Dilbert
Gadget Master
Made By Monkeys

Get these stories direct to your inbox - sign up for free E-newsletters >>

For more on memory, NAND, DRAM, SRAM and DDR content, see Components/Memory

Samsung leads firms in stacked DRAM initiative

Richard Wilson
Friday 07 October 2011 10:23

Samsung Electronics and Micron Technology have created an industry group to collaborate on the implementation of an open interface specification for a new memory technology called the Hybrid Memory Cube (HMC).

Micron and Samsung are the founding members of the Hybrid Memory Cube Consortium (HMCC), and will work with fellow developers Altera, Open Silicon and Xilinx to bring the technology to market.

The aims of the initiative are to address memory bandwidth in high-end embedded systems.

"The term "memory wall" has been used to describe the problem. Breaking through the memory wall requires a new architecture that can provide increased density and bandwidth at significantly reduced power consumption," said the companies.

Details of HMC technology are vague, but it uses a stack of through-silicon-via (TSV) bonded DRAM die to improve memory density and data throughput.

The companies claim a x15 improvement in density over traditional DDR3 DRAM devices.

"This collaborative industry effort will serve as an accelerator for highly promising technology that will benefit the entire industry," said Jim Elliott, v-p memory marketing at Samsung Semiconductor.

"HMC is unlike anything currently on the radar," said Robert Feurle, Micron's Vice President for DRAM Marketing.

The consortium will initially define a specification to enable applications ranging from large-scale networking to industrial products and high-performance computing.

www.hybridmemorycube.org

Like

Add New Comment

Login

> MAIN INDEX

Securing London 2012 provider WORK Security Staff Apply now

Share the content

ShareThis

Most Viewed

Android Ice Cream Sandwich gets NFC stack
Posted: 11:20 17 Jan 2012

Tiny budget spy plane made from PCBs
Posted: 15:21 16 Jan 2012

Samsung's \$41bn 2012 investment dwarfs Japanese rivals' spend
Posted: 11:55 17 Jan 2012

LightSquared cannot coexist with GPS - US federal agencies
Posted: 10:36 16 Jan 2012

Samsung starts production of 46-inch transparent LCDs
Posted: 10:05 17 Jan 2012

Related Jobs

Optimus Se PCIe Exper
Posted: 00:00

Requero l Principal A Process Technologi 12207, Cambridge
Posted: 12:29

Optimus Se Consultant Hardware
Posted: 00:00

IC Resource ASIC Design/Veri Engineer -
Posted: 12:44

IC Resource Digital IC D Engineer - Germany
Posted: 08:41

Resources

Products



LEADING T PACK AS T WORLDWI MANUFACT OF FREQU CONTROL